

ABSTRACT

A polyamide resin composition comprises a polyamide resin component (A) and a metallic soap component (B), wherein the polyamide resin component (A) comprises a  
5 dicarboxylic acid component (a-1), which comprises a terephthalic acid component and an aromatic dicarboxylic acid component other than the terephthalic acid component and/or an aliphatic dicarboxylic acid component of 4 to 20 carbon atoms, and a diamine component (a-2), which  
10 comprises an aliphatic diamine component; and the metallic soap component (B) comprises a metallic soap comprising an aliphatic carboxylic acid and a monovalent or divalent metal salt . The polyamide resin composition has excellent heat resistance and is favorably used as a  
15 molding material for electric or electronic parts and automotive parts. The polyamide resin composition is excellent in flowability, mold-releasing properties and shot stability in the injection molding process.